



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ0503NSI		<b>Issued</b>		20. July 2018			
<b>MA#</b>		MA001295950							
<b>Package</b>		PG-TSDSON-8-25		<b>Weight*</b>		34.49 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.267	0.77	0.77	7733	7733	
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		105		
		non noble metal	zinc	7440-66-6	0.015	0.04		421	
		non noble metal	iron	7439-89-6	0.291	0.84		8428	
wire	non noble metal	non noble metal	copper	7440-50-8	11.804	34.22	35.11	342216	351170
		non noble metal	copper	7440-50-8	0.017	0.05	0.05	479	479
		encapsulation	organic material	carbon black	1333-86-4	0.036	0.11		1055
plastics	plastics	epoxy resin	-	1.874	5.43		54325		
		inorganic material	silicondioxide	60676-86-0	16.283	47.21	52.75	472049	527429
		leadfinish	non noble metal	tin	7440-31-5	0.400	1.16	1.16	11602
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	589	589	
solder	noble metal	silver	7440-22-4	0.011	0.03		324		
		non noble metal	tin	7440-31-5	0.009	0.03		259	
		non noble metal	lead	7439-92-1	0.427	1.24	1.30	12382	12965
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
		non noble metal	zinc	7440-66-6	0.004	0.01		106	
		non noble metal	iron	7439-89-6	0.073	0.21		2113	
		non noble metal	copper	7440-50-8	2.959	8.58	8.80	85788	88033
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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